

IGBT4 Modules

SKM1400GB12P4

Features*

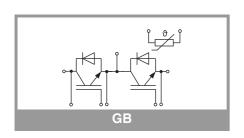
- · Symmetrical current sharing
- Low-inductive module design
- High mechanical robustness
- UL recognized, file no. E63532

Typical Applications

- Motor Drives
- UPS Systems
- Solar Inverters

Remarks

Recommended $T_{jop} = -40 \dots +150^{\circ}C$



Absolute Maximum Ratings							
Symbol	Conditions		Values	Unit			
IGBT				'			
V _{CES}	T _j = 25 °C		1200	V			
Ic	T _j = 175 °C	T _c = 25 °C	2165	Α			
		T _c = 100 °C	1453	Α			
I _{Cnom}			1400	Α			
I _{CRM}			2800	Α			
V _{GES}			-20 20	V			
t _{psc}	$V_{CC} = 800 \text{ V}$ $V_{GE} \le 15 \text{ V}$ $V_{CES} \le 1200 \text{ V}$	T _j = 150 °C	10	μs			
Tj			-40 175	°C			
Inverse di	ode						
V_{RRM}	T _j = 25 °C		1200	V			
I _F	T _j = 175 °C	T _c = 25 °C	1768	Α			
		T _c = 100 °C	1135	Α			
I _{FRM}		<u> </u>	2800	Α			
I _{FSM}	t _p = 10 ms, sin 180°, T _j = 25 °C		7296	Α			
Tj			-40 175	°C			
Module	•			•			
T _{stg}			-40 150	°C			
V _{isol}	AC sinus 50 Hz, t = 1 min		4000	V			

Characteristics								
Symbol	Conditions		min.	typ.	max.	Unit		
IGBT	'							
V _{CE(sat)}	I _C = 1400 A	T _j = 25 °C		1.75	2.07	V		
	V _{GE} = 15 V chiplevel	T _j = 150 °C		2.18	2.44	V		
V_{CE0}	chiplevel	T _j = 25 °C		0.80	0.90	V		
		T _j = 150 °C		0.70	0.80	V		
r _{CE}	V _{GE} = 15 V	T _j = 25 °C		0.68	0.83	mΩ		
	chiplevel	T _j = 150 °C		1.06	1.17	mΩ		
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 49.2$	mA	5.1	5.8	6.4	V		
I _{CES}	$V_{GE} = 0 \text{ V}, V_{CE} = 12$			6	mA			
C _{ies}	V 05.V	f = 1 MHz		81.6		nF		
C _{oes}	$V_{CE} = 25 \text{ V}$ $V_{GF} = 0 \text{ V}$	f = 1 MHz		5.28		nF		
C _{res}	VGE - O V	f = 1 MHz		4.50		nF		
Q_{G}	V _{GE} = - 8 V+ 15 V			7500		nC		
R _{Gint}	T _j = 25 °C			8.0		Ω		
t _{d(on)}	$V_{CC} = 600 \text{ V}$	T _j = 150 °C		353		ns		
t _r	$I_{C} = 1400 \text{ A}$ $V_{GE} = +15/-15 \text{ V}$ $R_{G \text{ on}} = 1 \Omega$ $R_{G \text{ off}} = 1 \Omega$	T _j = 150 °C		119		ns		
E _{on}		T _j = 150 °C		150		mJ		
t _{d(off)}		T _j = 150 °C		803		ns		
t _f	di/dt _{on} = 11 kA/μs	T _j = 150 °C		171		ns		
E _{off}	$\begin{array}{l} \mbox{di/dt}_{\mbox{off}} = 6.9 \ \mbox{kA/}\mu\mbox{s} \\ \mbox{dv/dt} = 3300 \ \mbox{V/}\mu\mbox{s} \\ \mbox{L}_{\mbox{s}} = 36 \ \mbox{nH} \end{array}$	T _j = 150 °C		277		mJ		
R _{th(j-c)}	per IGBT				0.02	K/W		
R _{th(c-s)}	per IGBT (λ _{grease} =0		0.008		K/W			



SEMITRANS® 10

IGBT4 Modules

SKM1400GB12P4

Features*

· Symmetrical current sharing

• Low-inductive module design

High mechanical robustness

• UL recognized, file no. E63532

Typical Applications

• Motor Drives

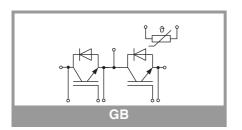
• UPS Systems

Solar Inverters

Remarks

Recommended $T_{jop} = -40 \dots +150^{\circ}C$

Characteristics								
Symbol	Conditions	min.	typ.	max.	Unit			
Inverse diode								
$V_F = V_{EC}$	I _F = 1400 A	T _j = 25 °C		2.06	2.37	V		
	V _{GE} = 0 V chiplevel	T _j = 150 °C		2.03	2.35	٧		
V_{F0}	v _{F0} chiplevel	T _j = 25 °C		1.30	1.50	V		
		T _j = 150 °C		0.90	1.10	V		
r _F	chiplevel	T _j = 25 °C		0.54	0.62	mΩ		
		T _j = 150 °C		0.81	0.89	mΩ		
I _{RRM}	I _F = 1400 A	T _j = 150 °C		1014		Α		
Q_{rr}	di/dt _{off} = 11 kA/μs V _{GE} = -15 V	T _j = 150 °C		214		μC		
E _{rr}	$V_{CC} = 600 \text{ V}$	T _j = 150 °C		85		mJ		
R _{th(j-c)}	per diode			0.033	K/W			
R _{th(c-s)}	per diode (λ _{grease} =0.81 W/(m*K))			0.01		K/W		
Module								
L _{CE}				10		nΗ		
R _{CC'+EE'}	measured per switch, T _C = 25 °C		0.2			mΩ		
R _{th(c-s)1}	calculated without thermal coupling (λ _{grease} =0.81 W/(m*K))		0.0022			K/W		
R _{th(c-s)2}	including thermal coupling, T_s underneath module $(\lambda_{grease} = 0.81 \text{ W/(m}^+\text{K)})$			0.004		K/W		
Ms	to heat sink M5		4		6	Nm		
Mt		to terminals M8	8		10	Nm		
		to terminals M4	1.8		2.1	Nm		
W					1250	g		
Temperat	ure Sensor							
R ₁₀₀	T _c =100°C (R ₂₅ =5 kΩ)			493 ± 5%		Ω		
B _{100/125}	$R_{(T)}=R_{100}exp[B_{100/125}(1/T-1/T_{100})];T[K];$			3550 ±2%		K		



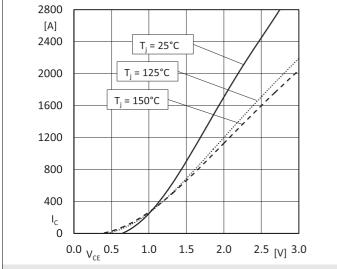


Fig. 1: Output characteristics IGBT (typical); $I_C = f(V_{CE})$; V_{GE} = 15V; (chiplevel)

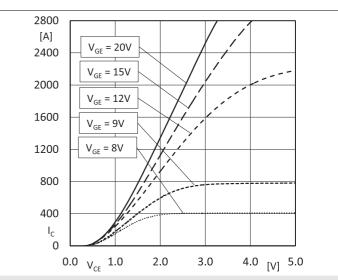


Fig. 2: Output characteristics IGBT (typical); $I_C = f(V_{CE})$; $T_i = 150 \,^{\circ}\text{C}$; (chiplevel)

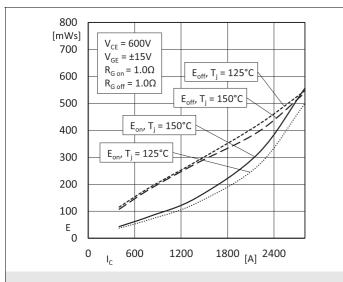


Fig. 3: Switching losses IGBT (typical); E=f(I_C)

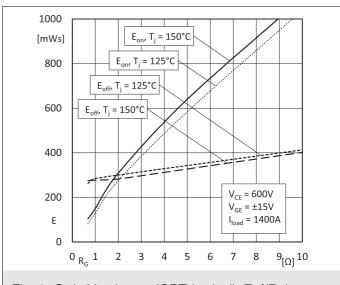


Fig. 4: Switching losses IGBT (typical); E=f(R_G)

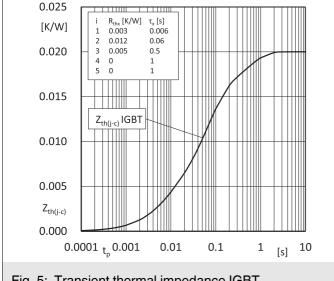


Fig. 5: Transient thermal impedance IGBT

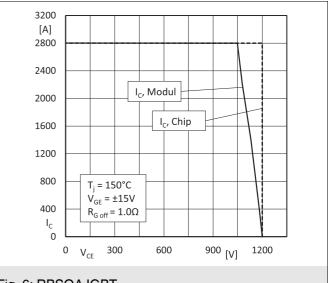


Fig. 6: RBSOA IGBT

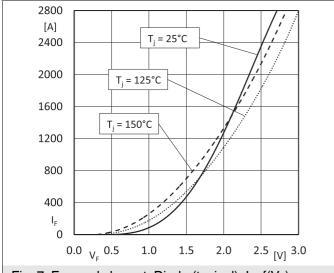


Fig. 7: Forward charact. Diode (typical); $I_F=f(V_F)$; (chiplevel)

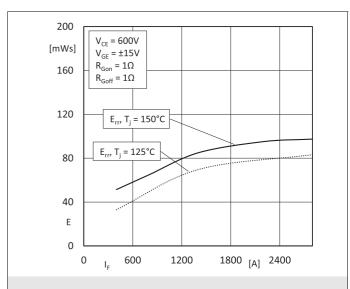


Fig. 8: Switching losses Diode (typical); E=f(I_F)

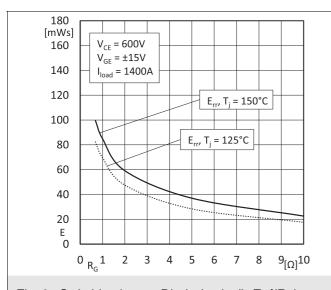


Fig. 9: Switching losses Diode (typical); E=f(R_G)

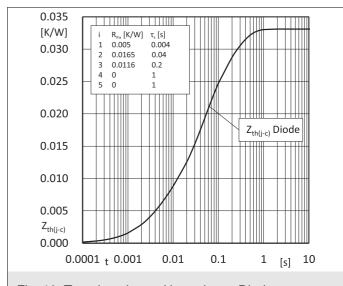
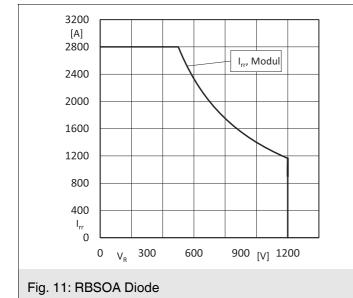
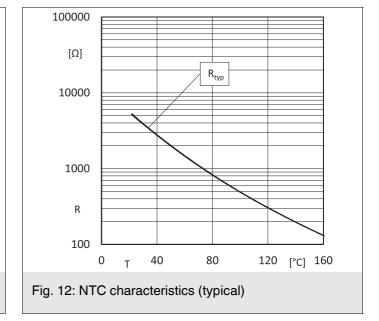
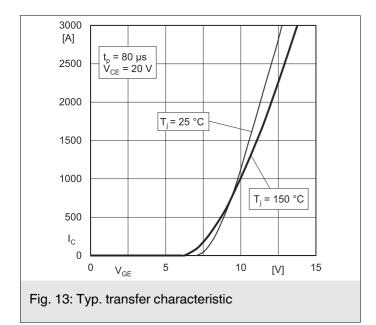


Fig. 10: Transient thermal impedance Diode







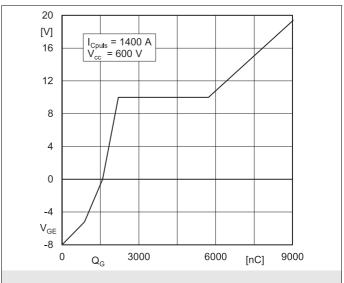
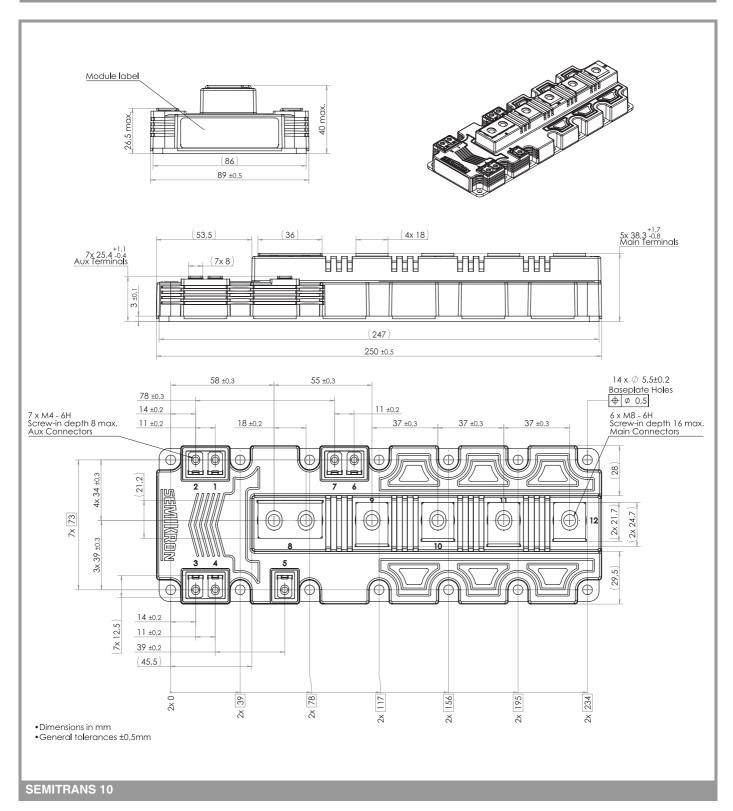
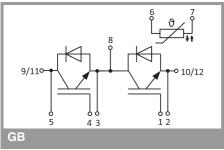


Fig. 14: Typ. gate charge characteristic





This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

*IMPORTANT INFORMATION AND WARNINGS

The specifications of SEMIKRON products may not be considered as guarantee or assurance of product characteristics ("Beschaffenheitsgarantie"). The specifications of SEMIKRON products describe only the usual characteristics of products to be expected in typical applications, which may still vary depending on the specific application. Therefore, products must be tested for the respective application in advance. Application adjustments may be necessary. The user of SEMIKRON products is responsible for the safety of their applications embedding SEMIKRON products and must take adequate safety measures to prevent the applications from causing a physical injury, fire or other problem if any of SEMIKRON products become faulty. The user is responsible to make sure that the application design is compliant with all applicable laws, regulations, norms and standards. Except as otherwise explicitly approved by SEMIKRON in a written document signed by authorized representatives of SEMIKRON, SEMIKRON products may not be used in any applications where a failure of the product or any consequences of the use thereof can reasonably be expected to result in personal injury. No representation or warranty is given and no liability is assumed with respect to the accuracy, completeness and/or use of any information herein, including without limitation, warranties of non-infringement of intellectual property rights of any third party. SEMIKRON does not assume any liability arising out of the applications or use of any product; neither does it convey any license under its patent rights, copyrights, trade secrets or other intellectual property rights, nor the rights of others. SEMIKRON makes no representation or warranty of non-infringement or alleged non-infringement of intellectual property rights of any third party which may arise from applications. Due to technical requirements our products may contain dangerous substances. For information on the types in question please contact the nearest SEMIKRON sales office. This document supersedes and replaces all information previously supplied and may be superseded by updates. SEMIKRON reserves the right to make changes.